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Part Number:

0541323862

Status:

Active

Overview:

ffc_fpc_smt

Description:

0.50mm (.020") Pitch FFC/FPC Connector, Right Angle, SMT, ZIF, Bottom Contact Style, 38 Circuits, 0.1µm (4µ") Gold (Au) Contact Plating

Documents:

3D Model

Drawing (PDF)

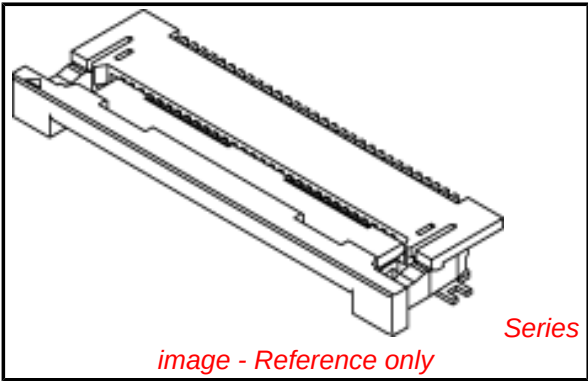
Product Specification PS-54132-061 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification	
UL	E29179
General	
Product Family	FFC/FPC Connectors
Series	54132
Overview	ffc_fpc_smt
Product Name	N/A
Physical	
Circuits (Loaded)	38
Color - Resin	Black, Natural
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Flammability	94V-0
Mated Height (in)	0.079 In
Mated Height (mm)	2.00 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Plating min: Mating (µin)	4
Plating min: Mating (µm)	0.1
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	N/A
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC
Electrical	
Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

54132Series

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10 9 8 7 6 5 4 3 2 1

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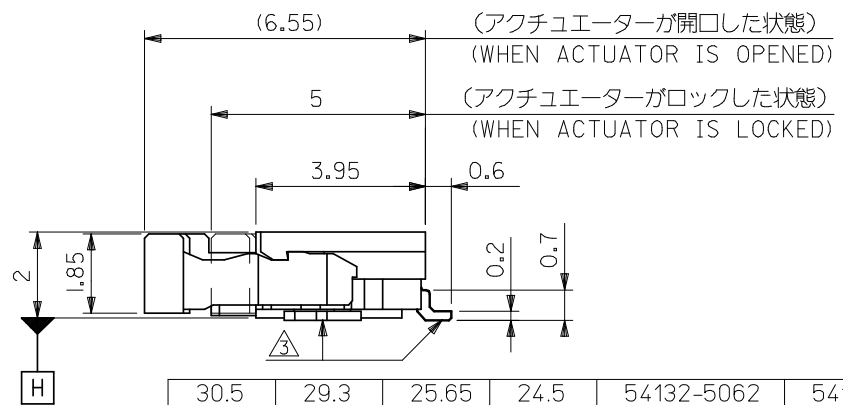
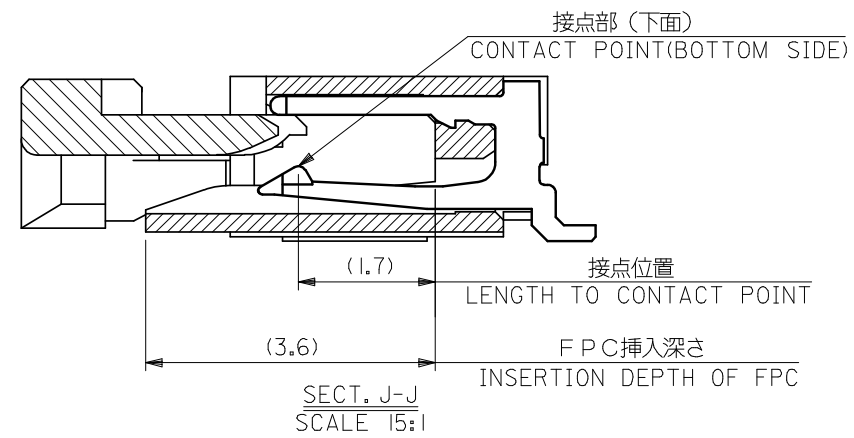
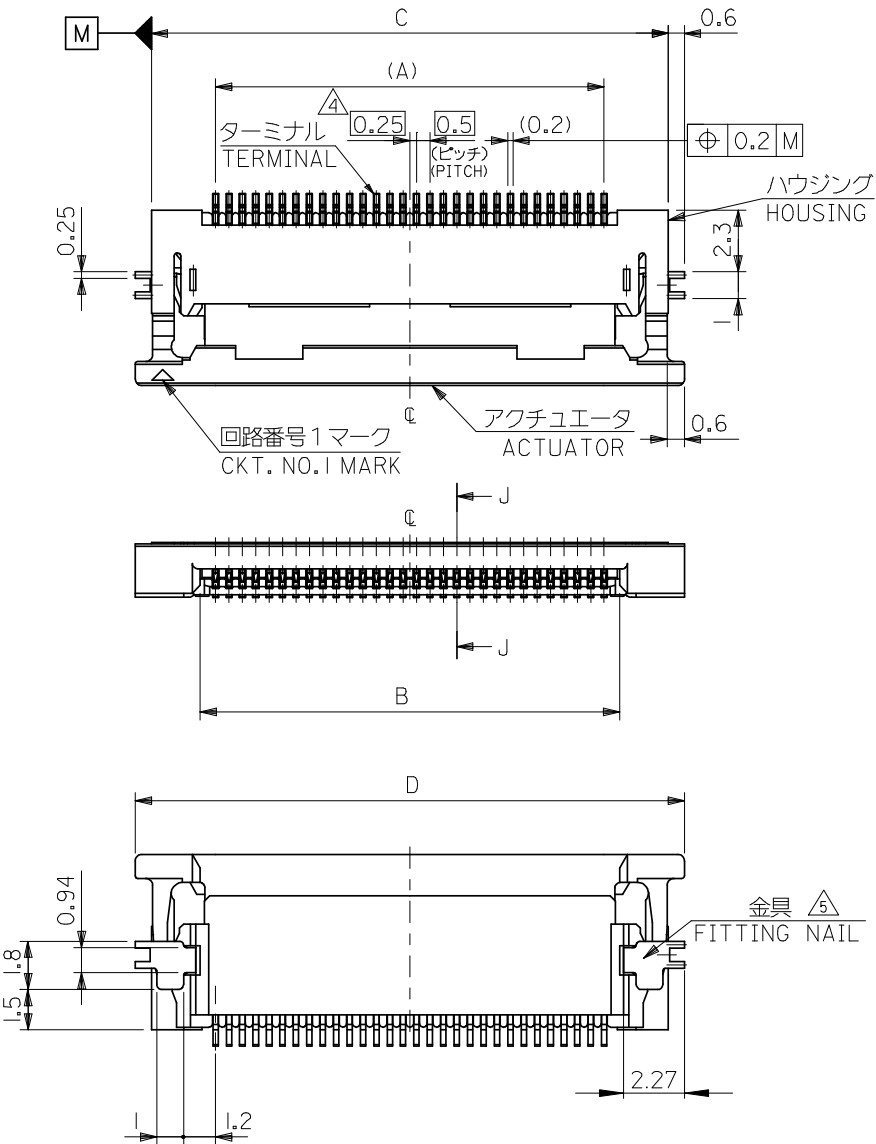
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30.5	29.3	25.65	24.5	54132-5062	54132-5068	50
28.0	26.8	23.15	22.0	54132-4562	54132-4568	45
27.0	25.8	22.15	21.0	54132-4362	54132-4368	43
25.5	24.3	20.65	19.5	54132-4062	54132-4068	40
24.5	23.3	19.65	18.5	54132-3862	54132-3868	38
23.5	22.3	18.65	17.5	54132-3662	54132-3668	36
23.0	21.8	18.15	17.0	54132-3562	54132-3568	35
22.5	21.3	17.65	16.5	54132-3462	54132-3468	34
22.0	20.8	17.15	16.0	54132-3362	54132-3368	33
21.5	20.3	16.65	15.5	54132-3262	54132-3268	32
20.5	19.3	15.65	14.5	54132-3062	54132-3068	30
D	C	B	A	EMBOSSED TAPE		MATERIAL. NO.
				ORDER No. オーダー番号		CKT.

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M.UMEDA		DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)			
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA		DATE 2004/09/27				
		30 OVER	±0.3	APPROVED BY N.UKITA		DATE 2004/09/27	MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-54132-064		1 OF 4		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

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D

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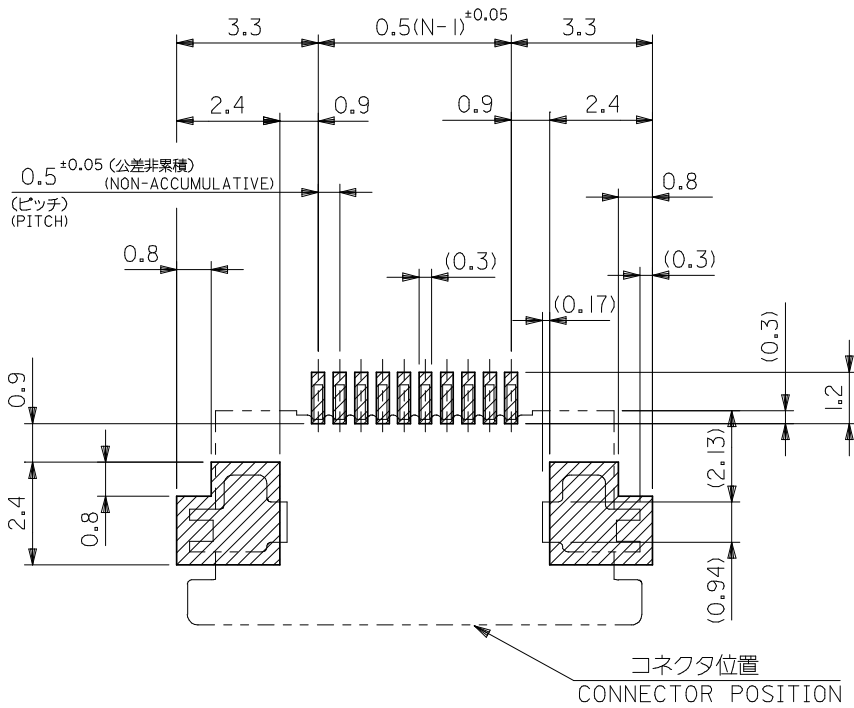
E

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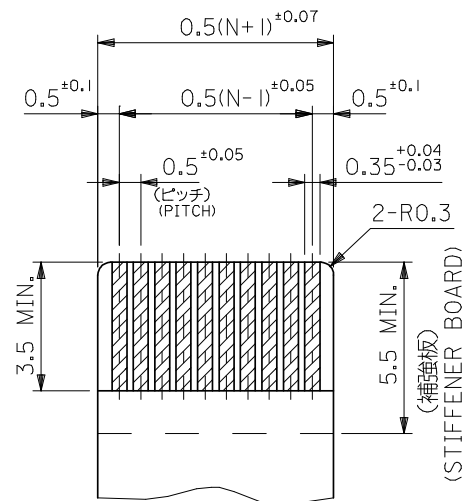
C

B

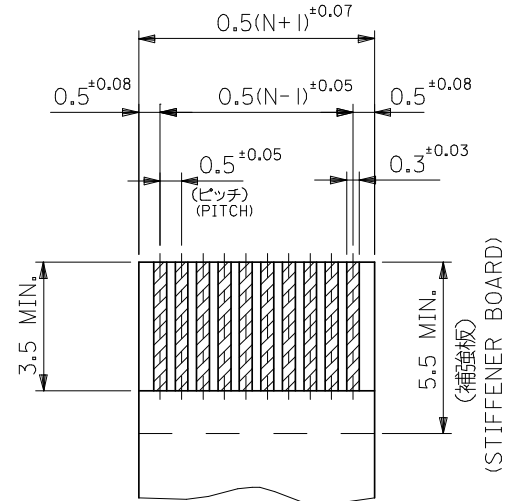
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参考基板レイアウト
RECOMMENDED PC BOARD PATTERN DIMENSION(REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記
NOTES

1. 使用材料
MATERIAL
ハウジング
HOUSING : 46ナイロン, UL94V-0
: 46NYLON
- アクチュエーター
ACTUATOR : PPS, UL94V-0
: PPS
- ターミナル
: 金メッキ
コンタクト部 0.1 MICRO METER MIN.
テール部 0.05 MICRO METER MIN.
: ニッケル下地 1.0 MICRO METER MIN.
- TERMINAL : GOLD PLATING
CONTACT PORTION: 0.1 MICRO METER MIN.
TAIL PORTION: 0.05 MICRO METER MIN.
: NI-PLATING: 0.1 MICRO METER MIN.
- 金具 : リン青銅 (t=0.2), 鍍メッキ 1.0~3.0 MICRO METER MIN.
: ニッケル下地 1.0~3.0 MICRO METER MIN.
- FITTING NAIL : PHOS-BRO, TIN-PLATE 1.0~3.0 MICRO METER MIN.
OVER NICKEL 1.0~3.0 MICRO METER MIN.

2. エンボステープ梱包時は、アクチュエーターがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54132-**69 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 [H] に対し上方向 0.1 MAX.、下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAIL FROM [H] UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
4. 偶数極に適用
APPLY FOR EVEN CIRCUIT.
5. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.

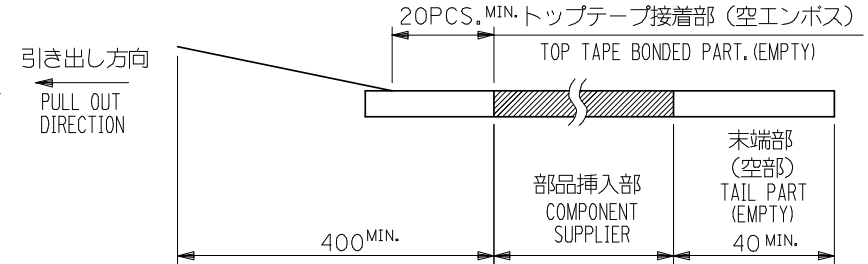
FPC/FFCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL : 35 micrometer or 50 micrometer

FPCについて:
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

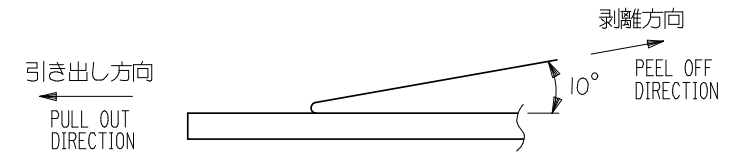
REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARYAWA APPR:NUKITA	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M.UMEDA		DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA		DATE 2004/09/27				
		30 OVER	±0.3	APPROVED BY N. UKITA		DATE 2004/09/27				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54132-064		2 OF 4		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

1. 梱包数量：1500個／リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



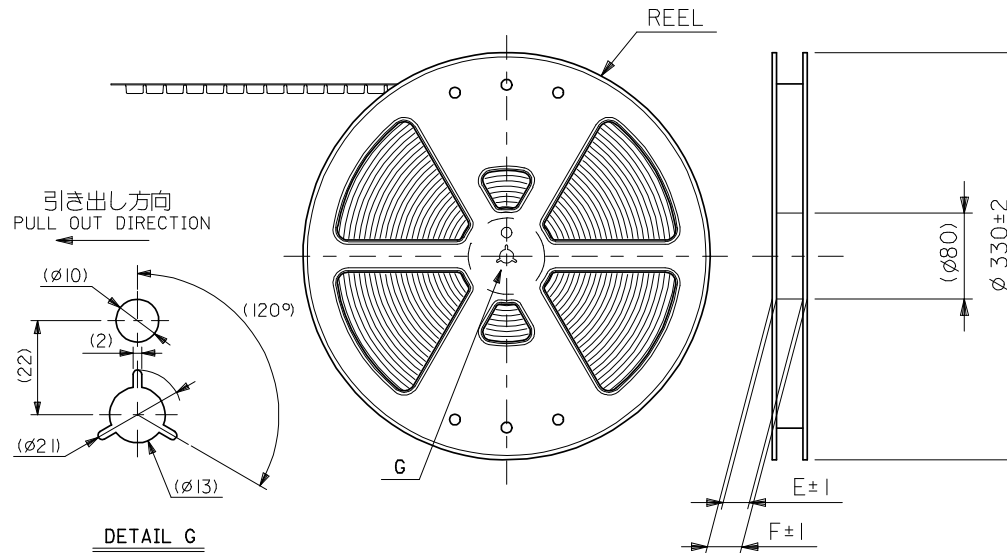
3. トップテープの剥離強度： 0.1N ～ 1.3N(10gf ～ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N(10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



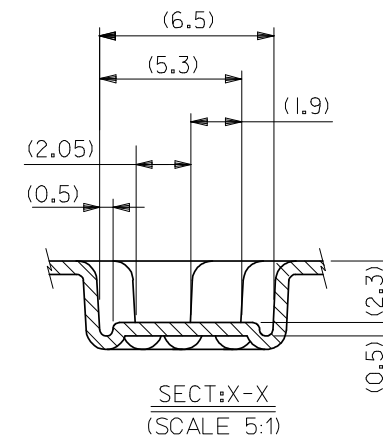
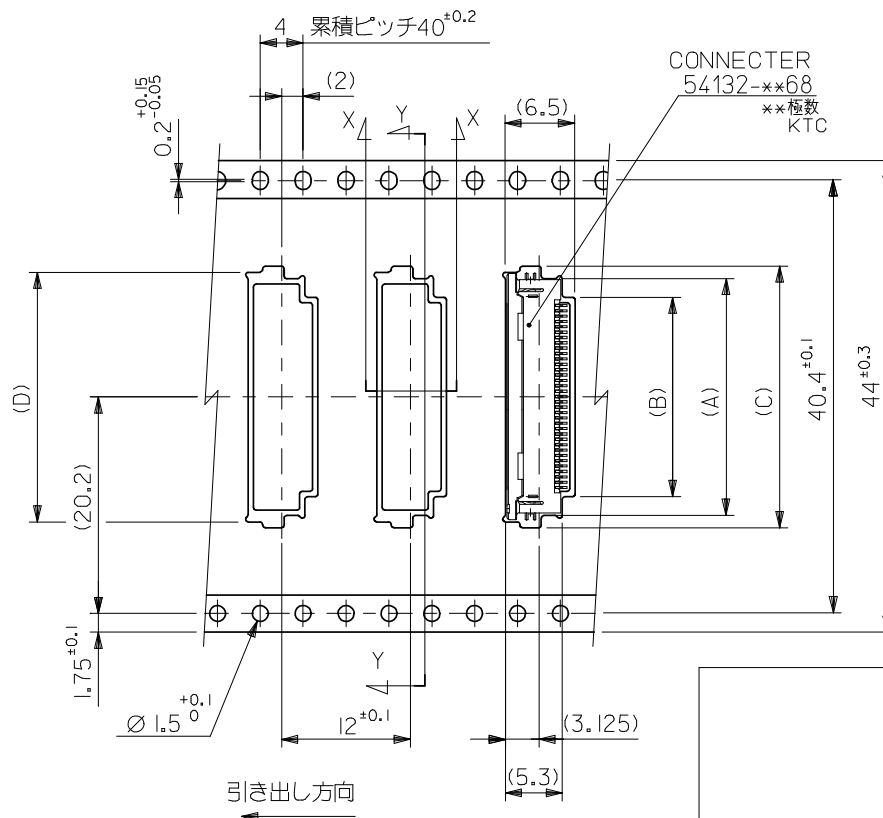
5. 材料 キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.



REVISED EC NO: J2008-4308 2008/06/27 DRWN:WABEI 2008/06/30 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY M.UMEDA	DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)				
		10 OVER 30 UNDER	± ---	CHECKED BY K.TOYODA	DATE 2004/09/27					
		30 OVER	± ---	APPROVED BY N.UKITA	DATE 2004/09/27	MOLEX INCORPORATED				
		ANGULAR	± --- °	MATERIAL NO. SEE SHEET 4		DOCUMENT NO. SD-54132-064			SHEET NO. 3 OF 4	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



44	49.4	45.4	30.8	31.9	26.1	29.6	54132-5062	50
			28.3	29.4	23.6	27.1	54132-4562	45
			27.3	28.4	22.6	26.1	54132-4362	43
			25.8	26.9	21.1	24.6	54132-4062	40
			24.8	25.9	20.1	23.6	54132-3862	38
			23.8	24.9	19.1	22.6	54132-3662	36
			23.3	24.4	18.6	22.1	54132-3562	35
			22.8	23.9	18.1	21.6	54132-3462	34
			22.3	23.4	17.6	21.1	54132-3362	33
			21.8	22.9	17.1	20.6	54132-3262	32
			20.8	21.9	16.1	19.6	54132-3062	30
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO. (EMBOSS PKG)	CKT.

REVISED	EC NO: J2008-4308	DRWN:MMABEI CH'K'D:THARUYAMA APPR:NUKITA	DESCRIPTION	REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					10 UNDER	± ---	DRAWN BY DATE M.UMEDA 2004/09/27		TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)				
					10 OVER 30 UNDER	± ---	CHECKED BY DATE K. TOYODA 2004/09/27						
					30 OVER	± ---	APPROVED BY DATE M.UMEDA 2004/09/27		molex MOLEX INCORPORATED				
					ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE TABLE THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
								SD-54132-064		4 OF 4			

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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